SS215 thru SS220

SURFACE MOUNT

SCHOTTKY BARRIER RECTIFIERS

REVERSE VOLTAGE - 150 to 100 Volts

FORWARD CURRENT - 2.0 Amperes

FEATURES

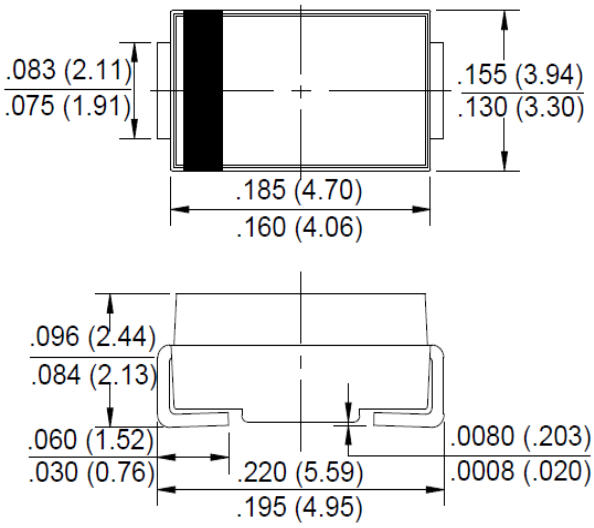
- ●For surface mounted applications
- ●Metal-Semiconductor junction with guarding
- ●Epitaxial construction
- ●Very low forward voltage drop
- ●High current capability
- ●Plastic material has UL flammability classification 94V-0
- ●For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

MECHANICAL DATA

- ●Case： Molded Plastic
- ●Polarity:Color band denotes cathode
- ●Weight: 0.003 ounces,0.093 grams

Note: Products with logo HY or hy are made by HY Electronic (Cayman) Limited.

SMB



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25℃ ambient temperature unless otherwise specified.

Single phase, half wave ,60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	SS215	SS220	UNIT
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	150	200	V
Maximum RMS Voltage	V_{RMS}	105	140	V
Maximum DC Blocking Voltage	V_{DC}	150	200	V
Maximum Average Forward Rectified Current @T_L=100 ℃	$I_{(AV)}$	2.0		A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed On Rated Load (JEDEC Method)	I_{FSM}	50		A
Maximum Forward Voltage at 2.0A DC	V_F	0.95		V
Maximum DC Reverse Current @T_J=25℃	I_R	1.0		mA
at Rated DC Blocking Voltage @T_J=100℃		20		
Typical Thermal Resistance (Note2)	$R_{\theta JL}$	25		℃/W
Operating Temperature Range	T_J	-55 to + 150		℃
Storage Temperature Range	T_{STG}	-55 to + 150		℃

NOTES:1.Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

2.Thermal resistance junction to lead.

3.The typical data above is for reference only.

RATING AND CHARACTERTIC CURVES
SS215 thru SS220

FIG. 1 - FORWARD CURRENT DERATING CURVE

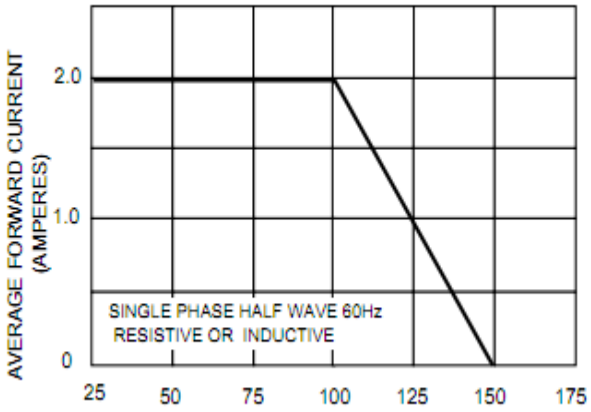


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

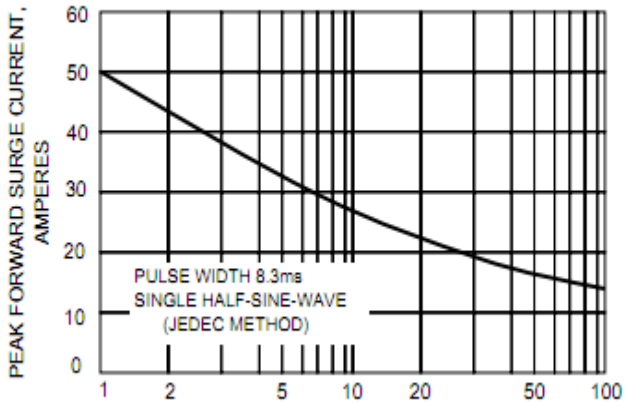


FIG.3-TYPICAL FORWARD CHARACTERISTICS

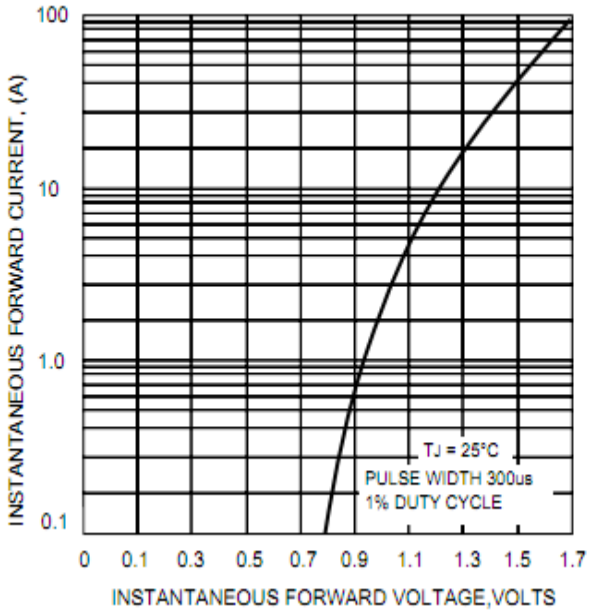


FIG.4-TYPICAL JUNCTION CAPACITANCE

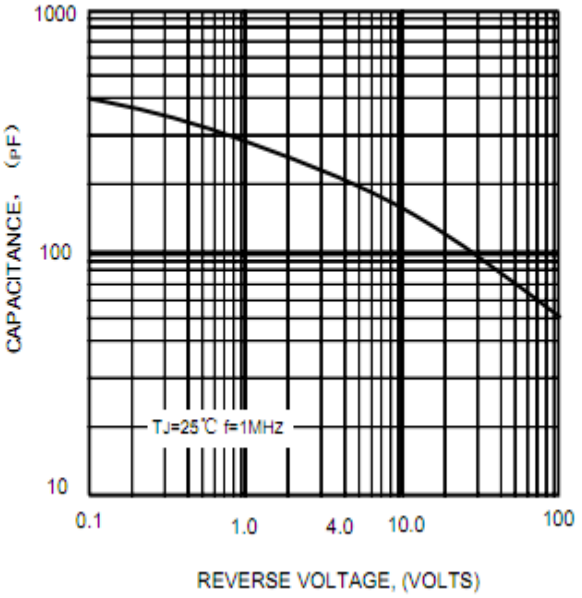
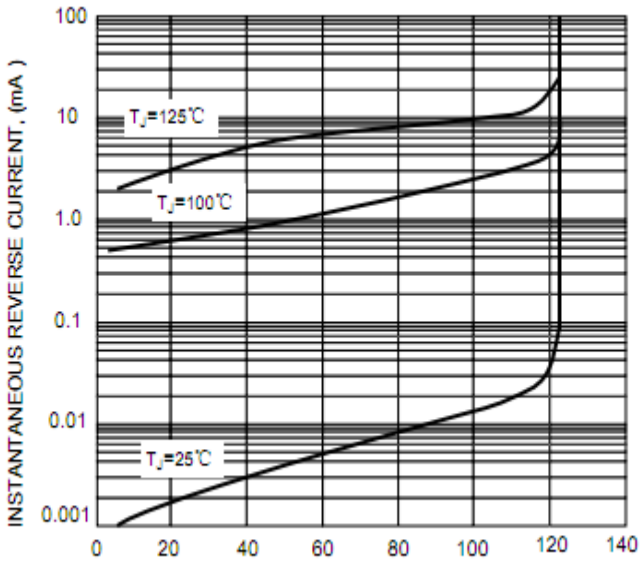


FIG.5-TYPICAL REVERSE CHARACTERISTICS



The cruve graph is for referenc

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